

Please see below for a partial list of funding opportunities.

PLEASE NOTE: Pivot E-mail Alerts, set up individually by faculty members, are Purdue's primary resource for timely funding information in all disciplines. More information about Pivot and other e-mail alert services and search tools may be found [here](#). Please contact Sue Grimes (sgrimes@purdue.edu) with any questions.

****** To receive this newsletter directly to your inbox, please sign up for the listserv by emailing listserv@lists.purdue.edu. Leave the subject blank and in the message body type: subscribe Weeklyfundingopps [your_first_name] [your_last_name]. Only *purdue.edu* e-mail addresses will be accepted. ******

1. **Limited Submissions:**

Preproposals and rankings should be submitted via Purdue's InfoReady portal (<https://purdue.infoready4.com/>). Purdue's open limited submission competitions, templates, and limited submission policy may be found at <http://www.purdue.edu/research/funding-and-grant-writing/limited-submissions.php>. For any case in which the number of preproposals received is no more than the number of proposals allowed by the sponsor, the OOR will notify the PI(s) that an internal competition will be unnecessary. Questions should be addressed to EVPRPlimited@purdue.edu.

Limited Submission: None this week

2. **Selected Funding Opportunities:**

[NSF Enabling Access to the Semiconductor Chip Ecosystem for Design, Fabrication, and Training \(Chip Design Hub\)](#) This solicitation seeks proposals to establish and manage a community infrastructure that supports the *entire* IC chip design process beginning from behavior/structural description at the Register Transfer Level (RTL) or above to GDSII fabrication mask file generation. The infrastructure should provide licensing, access, and maintenance of (i) commercial and/or open-source EDA tools necessary for the end-to-end IC chip design and verification process, and (ii) design PDK/IPs at various CMOS technology nodes (potentially including emerging technologies), as well as support for multi-project-chip (MPC) integration. Further, proposals should include efforts to develop, curate, and host educational/tutorial materials on the entire IC chip design flow to help train the next generation of IC designers and researchers. Deadline: April 4

[NSF Dear Colleague Letter: Assessing Societal and Economic Impacts of Place-Based Innovation](#) With this Dear Colleague Letter (DCL), the NSF's Directorate for Technology, Innovation and Partnerships (TIP) announces its intention to invest in EAGER proposals that will advance the state of the art in assessing the societal and economic impacts of place-based innovation. The subsequent EAGER awards will advance research that addresses gaps in publicly available data and associated knowledge to adequately and appropriately benchmark activities in place-based innovation grounded in integrating research and development (R&D), translation, and workforce development (WFD), with emphases on how we leverage the full spectrum of diversity, equity, inclusion, and accessibility (DEIA) as well as leveraging of cross-sector partnerships. This DCL invites transdisciplinary teams to develop convergent and potentially transformative research proposals to address these gaps, and thereby increase the understanding of, and data surrounding, the elements of a regional innovation ecosystem and the various ways in which they interact and intersect with one another. Deadline: January 29

[NSF Dear Colleague Letter: Funding Opportunities for Engineering Research in Microelectronics and Semiconductors](#) The Directorate for Engineering encourages the submission of all types of research and education proposals related to microelectronics and semiconductors, including proposals in the following areas: Advanced packaging; Heterogenous integration; CMOS+X; Devices based on 2D materials; Wide-bandgap and

ultrawide-bandgap semiconductor devices and circuits; Semiconductor optoelectronic and magneto-electronic devices; Low-power devices and electronics; Energy harvesting; Quantum engineering using semiconductor technologies; Unconventional computing; Artificial intelligence (AI) devices and chips; Analog and high frequency devices; Internet of Things (IoT) chips; Devices for extreme environments; Security features in semiconductors; Thermal management of semiconductor electronics; Device characterization and modeling; Environmentally sustainable manufacture of semiconductors; and Semiconductor manufacturing processes. Deadline: April 30

[NSF Dear Colleague Letter: Funding Opportunities for Engineering Research to Achieve Net-Zero Climate Goals by 2050](#) With this Dear Colleague Letter, the U.S. National Science Foundation (NSF) Directorate for Engineering (ENG) encourages the submission of research and education proposals related to Net-Zero Climate Goals, including innovations to create a Circular Economy. The Engineering Directorate encourages the submission of Net-Zero-related proposals to the ENG core programs, and to other relevant programs. Deadline: April 30

[NSF Dear Colleague Letter: Neurobiology in Changing Ecosystems \(NiCE\)](#) With this Dear Colleague Letter (DCL), programs in the National Science Foundation's (NSF) Directorate for Biological Sciences' (BIO) Division for Integrative Organismal Systems (IOS) and The Kavli Foundation's Neurobiology and Changing Ecosystems Initiative encourage submission of research proposals that advance the field of neurobiology in changing ecosystems during fiscal year 2024 (through September 30, 2024). The opportunity described in this DCL encourages proposals that emphasize interdisciplinary collaborations and integrate diverse methodologies, including environmental monitoring techniques, behavioral and physiological experiments, ecological and evolutionary modeling, combined with traditional approaches in neuroscience investigation. Deadline: On-going through September 30

[NIH-NHGRI Technology Development Coordinating Center \(U24\)](#) NHGRI seeks to fund a Coordinating Center that will expand the support and coordination of technology development efforts funded by NHGRI. The goal is to accelerate technology development and progress in the field of genomics. Varied expertise is required, especially prior experience in coordinating large and complex multidisciplinary collaborative research efforts and appropriate expertise in the scientific areas covered by the GTP. Deadline: April 2

[NIH Notice of Special Interest \(NOSI\): Administrative Supplement for Research and Capacity Building Efforts Related to Bioethical Issues](#) The NIH Office of Science Policy (OSP) within the Office of the Director (OD) announces the availability of administrative supplements to support 1) research on bioethical issues to develop or support the development of an evidence base that may inform future policy directions, and/or 2) certain efforts to develop or augment bioethics research capacity. Applicants may propose to supplement parent awards focused on bioethics or biomedical and/or health-related behavioral research. The proposed bioethics question, issue, or topic must be clearly articulated. All applications must be within the scope of the parent award. Deadline: April 1

[DOD Engineer Research and Development Center \(ERDC\) Broad Agency Announcement](#) The ERDC is responsible for conducting research in the broad fields of hydraulics, dredging, coastal engineering, instrumentation, oceanography, remote sensing, geotechnical engineering, earthquake engineering, soil effects, vehicle mobility, self-contained munitions, military engineering, geophysics, pavements, protective structures, aquatic plants, water quality, dredged material, treatment of hazardous waste, wetlands, physical/mechanical/chemical properties of snow and other frozen precipitation, infrastructure and environmental issues for installations, computer science, telecommunications management, energy, facilities maintenance, materials and structures, engineering processes, environmental processes, land and heritage conservation, and ecological processes. This announcement is continuously open; pre-proposals may be submitted and will be reviewed at any time throughout the year. Deadline: On-going

[USDA-NIFA Organic Agriculture Research and Extension Initiative \(OREI\)](#) The Organic Agriculture Research and Extension Initiative (OREI) seeks to solve critical organic agriculture issues, priorities, or problems through the integration of research, education, and Extension activities. OREI funds projects that will enhance the ability of

producers and processors who have already adopted organic standards to grow and market high-quality organic agricultural products. Priority concerns include biological, physical and social sciences, including economics.
Deadline: February 15

[USDA-RMA Risk Management Education Partnership Program](#) The purpose of this competitive program is to deliver risk management training to U.S. agricultural producers to assist them in managing production, marketing, legal, financial, and human risk. The program gives priority to: (1) educating producers of crops currently not insured under Federal crop insurance, specialty crops, and underserved commodities, including livestock and forage and (2) providing collaborative partnerships to develop and deliver crop insurance education and risk management training. Priority areas include: Climate smart agriculture; equity and opportunity for historically underserved producers; Organic and specialty crops; Whole-farm revenue protection (WFRP) and micro farm trainings. A training session for potential applicants will be held on January 25 and 30.
Deadline: March 4

3. **Other:**

[DOE-NETL Request for Information for Carbon Basin Assessment and Storage Evaluation \(CarbonBASE\)](#)